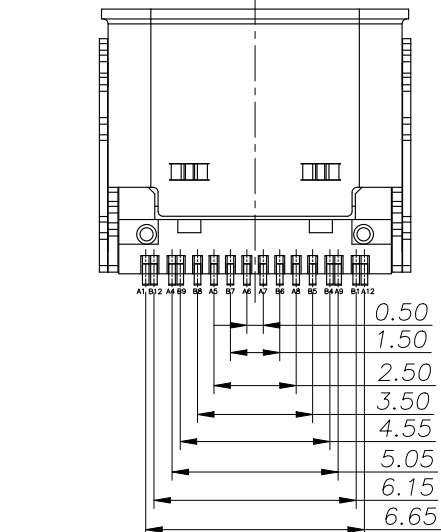
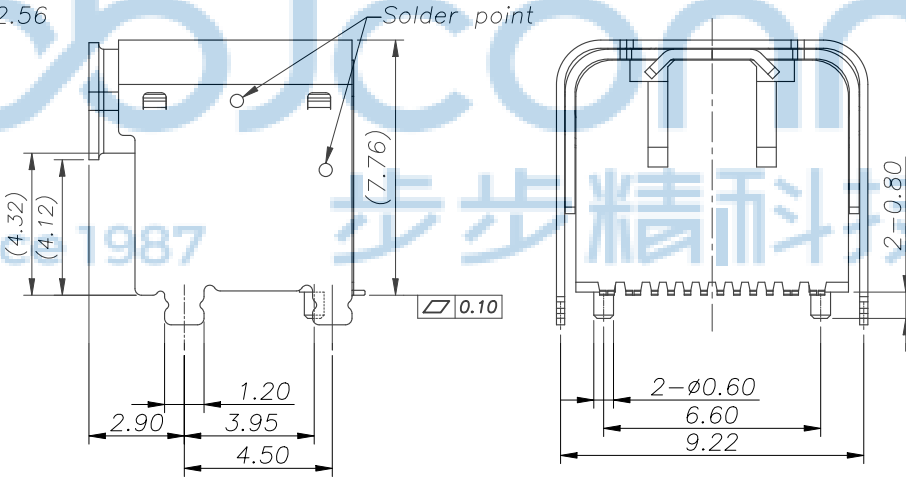
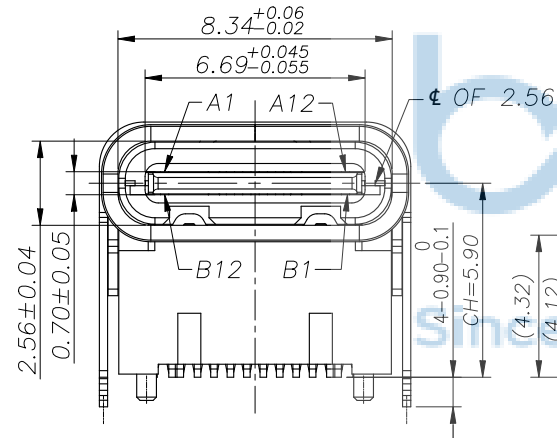
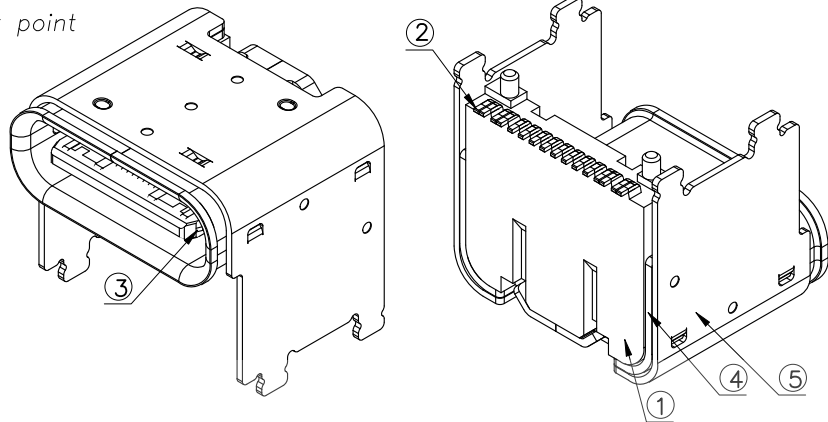
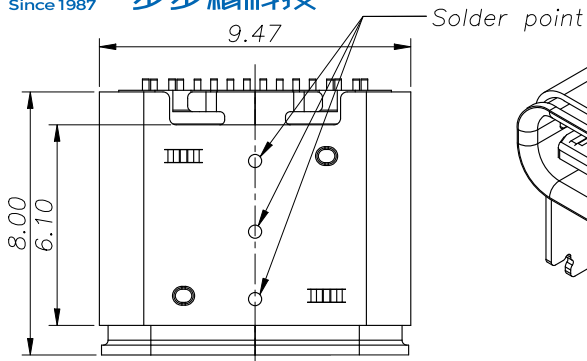


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

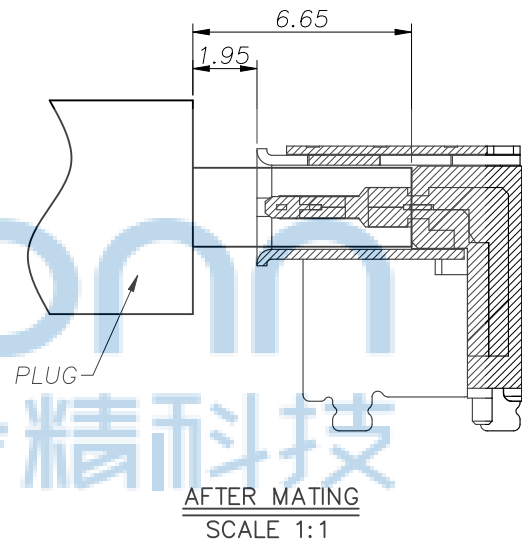
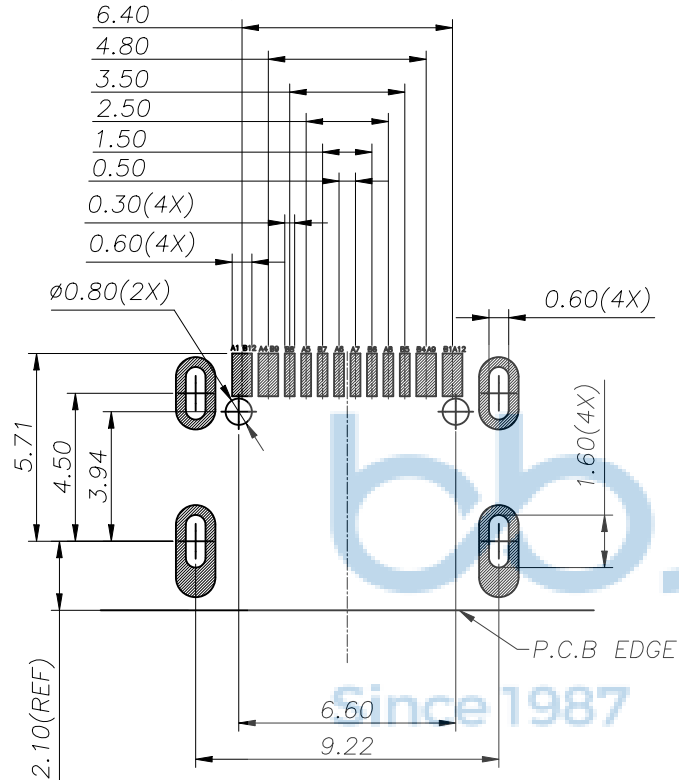


NOTE:

- MATERIAL SPECIFICATION:**
 - HOUSING: LCP Apple white
 - CONTACTS: C2680, T=0.15mm
 - MID PLATE: SUS301, T=0.15mm
 - INSIDE SHELL: SUS304, T=0.30mm
 - OUTSIDE SHELL: SUS304, T=0.25mm
- PLATING SPECIFICATION:**
 - CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au 1u" PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW)
 - GOLD FLASH PLATING ON SOLDER AREA
 - OUTSIDE SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
- MECHANICAL PERFORMANCE,**
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,**
 - CURRENT RATING: 5A
VOLTAGE RATING: 20V
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
 - LOW CONTACT RESISTANCE: INITIAL 40MΩ
AFTER 50MΩ
- ENVIRONMENTAL PERFORMANCE:**
 - OPERATING TEMPERATURE: -30°C~+80°C.
- IR REFLOW:**
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co., Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司	
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3' X'': ±2' X'X': ±1'	
APPD.	JM_Zheng	NAME: TYPE-C 16P 母座 SMT C2680端子 镀金1U 板上四脚插 带柱 垫高4.3 外壳两个焊点 LCP苹果白 L=8.0 CH=5.90 编带	
CHKD.	LYX	PJ. NO.: UC.01.51-11-0022	
DR.	TSP	SIZE: A4 DRW NO.:	
PDWG.NO:	0100-2	FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3	

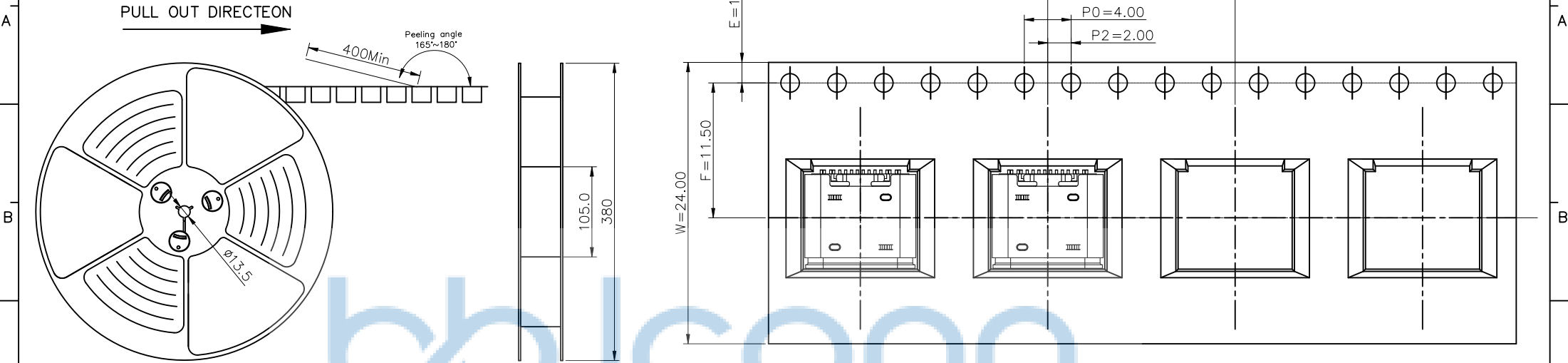


RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)
TOLERANCE FOR PCB LAYOUT IS ± 0.05

USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND

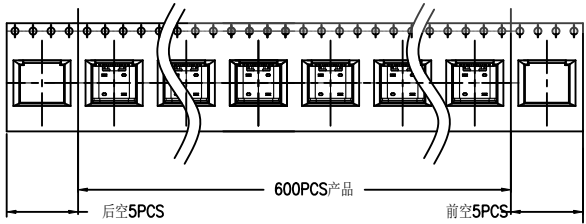
THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co., Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 .X: ± 0.38 .X': $\pm 3'$.XX: ± 0.25 .X': $\pm 2'$.XXX: ± 0.13 .XX': $\pm 1'$		NAME: TYPE-C 16P 母座 SMT C2680 端子 镀金1U 板上四脚插 带柱 垫高4.3 外壳两个焊点 LCP苹果白 L=8.0 CH=5.90 编带	
APPD.	JM_Zheng	PJ. NO.: UC.01.51-11-0022		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG. NO:	0100-2	DR.	TSP	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 2/3



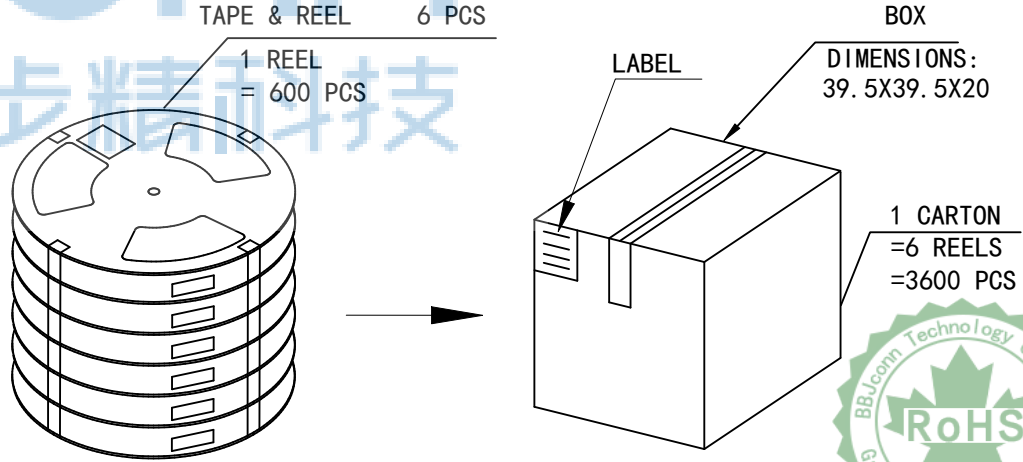
NOTES

1. 帶子引導長度
LEAD TAPE LENGTH
出料方向
PULL OUT DIRECTEON

出料方向
PULL OUT DIRECTEON



2. 上帶剝力力為：0.1~1.3N(10.2gf~130gf)
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N(10.2gf~130gf)
出貨運輸過程中一定注意：
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT：
卷帶在運輸過程中不能散開
PEELING OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION



包裝明細表 (The detail of the packing) Carton						
產品料號 (Product No.)	包裝容量 (Packing Capacity)			重量 Weight (Kg)		
	pcs/box	boxes/Carton	Pcs/Box	N. W. /Pcs	N. W. /Box	G. W. /Box
UC. 01. 51-11-0022	600	6	3600	----	----	----

THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co., Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 .X: ±0.38 .X': ±3" .XX: ±0.25 .X'': ±2" .XXX: ±0.13 .X''': ±1"		NAME: TYPE-C 16P 母座 SMT C2680 端子 鍍金1U 板上四腳插 帶柱 墊高4.3 外殼兩個焊點 LCP 蘋果白 L=8.0 CH=5.90 編帶	
APPD.	JM_Zheng	PJ. NO.: UC. 01. 51-11-0022		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG. NO:	0100-2	DR.	TSP	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 3/3